

What is claimed is:

1. A polishing agent for polishing a surface of a target object, said polishing agent comprising mother particles and abrading particles on surfaces of said mother particles.

2. The polishing agent of claim 1 wherein said abrading particles remain on said mother particles while said polishing agent is being used to polish said target object.

3. The polishing agent of claim 2 wherein the average diameter of said abrading particles is $1/500$ - $1/5$ of the average diameter of said mother particles.

4. A method of producing the polishing agent of claim 1, said method comprising the step of adding said mother particles into a polishing liquid in which said abrading particles are dispersed and the step of stirring together said mother particles and said polishing liquid.

5. A method of using the polishing agent of claim 1 and a polishing means to polish said target object; said method comprising the steps of;
supplying a specified amount of said polishing agent between said polishing means and said target object to be polished; and
causing said polishing means to move relative to said target object while keeping said polishing means practically in contact with said target object.

6. The method of claim 5 wherein said polishing means comprises a flat and smooth tape.

7. The method of claim 6 wherein said tape is rotated at a specified rotational speed.

8. The method of claim 5 wherein said polishing means comprises a lapping plate.

9. The method of claim 8 wherein said lapping plate is rotated at a specified
5 rotational speed while a lapping process is carried out on said target object.

FIG. 4 is a schematic diagram of a lapping process.